XP04878

Silicon N-channel MOSFET

For switching

■ Features

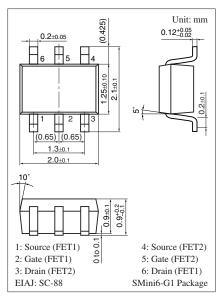
- Allowing 2.5 V drive
- Incorporating a built-in gate protection-diode
- S-Mini type 6-pin package, reduction of the mounting area and assembly cost by one half

■ Basic Part Number

• 2SK3539 × 2

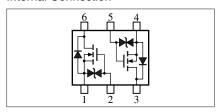
■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Drain-source surrender voltage	V _{DSS}	50	V
Gate-source voltage (Drain open)	V_{GSO}	±7	V
Drain current	I_{D}	100	mA
Peak drain current	I_{DP}	200	mA
Total power dissipation	P_{T}	150	mW
Channel temperature	T _{ch}	150	°C
Storage temperature	T _{stg}	-55 to +150	°C



Marking Symbol: 7Y

Internal Connection

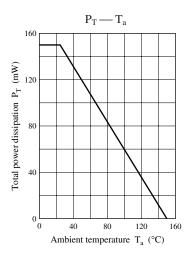


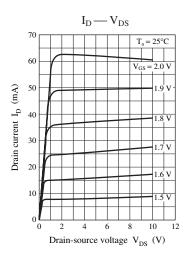
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

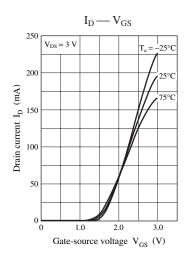
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Drain-source surrender voltage	V _{DSS}	$I_D = 10 \mu\text{A}, V_{GS} = 0$	50			V
Drain-source cutoff current	I _{DSS}	$V_{DS} = 50 \text{ V}, V_{GS} = 0$			1.0	μΑ
Gate-source cutoff current	I _{GSS}	$V_{GS} = \pm 7 \text{ V}, V_{DS} = 0$			±5	μΑ
Gate threshold voltage	V _{th}	$I_D = 1 \mu A, V_{DS} = 3 V$	0.9	1.2	1.5	V
Drain-source ON resistance	R _{DS(on)}	$I_D = 10 \text{ mA}, V_{GS} = 2.5 \text{ V}$		8	15	Ω
		$I_D = 10 \text{ mA}, V_{GS} = 4.0 \text{ V}$		6	12	
Forward transfer admittance	Yfs	$I_D = 10 \text{ mA}, V_{GS} = 4.0 \text{ V}$	20	60		mS
Short-circuit forward transfer	C _{iss}	$V_{DS} = 3 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		12		pF
capacitance (Common-source)						
Short-circuit output capacitance (Common-source)	C _{oss}			7		pF
Reverse transfer capacitance	C _{rss}			3		pF
(Common-source)						
Turn-on time	t _{on}	$V_{DD} = 3 \text{ V}, V_{GS} = 0 \text{ V to } 3 \text{ V}, R_{L} = 470 \Omega$		200		ns
Turn-off time	t _{off}	$V_{DD} = 3 \text{ V}, V_{GS} = 3 \text{ V to } 0 \text{ V}, R_L = 470 \Omega$		200		ns

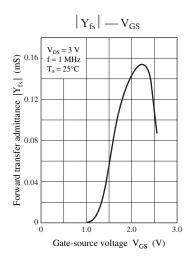
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

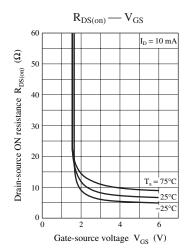
Panasonic

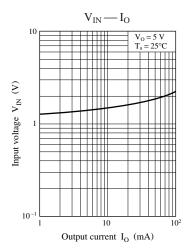












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